

Title (en)

METHOD FOR TREATING A TEMPORARILY BONDED PRODUCT WAFER

Title (de)

VERFAHREN ZUR BEHANDLUNG EINES TEMPORÄR GEBONDETEN PRODUKTWAFERS

Title (fr)

PROCÉDÉ DE TRAITEMENT D'UNE TRANCHE PRODUITE LIÉE TEMPORAIREMENT

Publication

**EP 2532024 A1 20121212 (DE)**

Application

**EP 10787688 A 20101123**

Priority

- DE 102010007127 A 20100205
- EP 2010007098 W 20101123

Abstract (en)

[origin: WO2011095189A1] The invention relates to a method for treating a product wafer temporarily bonded to a carrier wafer, comprising the following steps: grinding and/or back-thinning the product wafer on a flat side facing away from the carrier wafer to a product wafer thickness D of < 150 µm, in particular < 100 µm, preferably < 75 µm, more preferably < 50 µm, especially preferably < 30 µm, and after the grinding and/or back-thinning, treating the surface of the flat side using means for reducing an, in particular structural, internal stress of the product wafer.

IPC 8 full level

**H01L 21/683** (2006.01)

CPC (source: EP KR US)

**H01L 21/304** (2013.01 - KR); **H01L 21/683** (2013.01 - KR); **H01L 21/6835** (2013.01 - EP KR US); **H01L 21/6836** (2013.01 - EP US); **H01L 2221/68327** (2013.01 - EP US); **H01L 2221/6834** (2013.01 - EP US)

Citation (search report)

See references of WO 2011095189A1

Citation (examination)

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Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**DE 102010007127 A1 20110811**; CN 102725838 A 20121010; CN 102725838 B 20160302; EP 2532024 A1 20121212; JP 2013519218 A 20130523; KR 101822669 B1 20180308; KR 20120120198 A 20121101; SG 182703 A1 20120830; TW 201145373 A 20111216; TW I525677 B 20160311; US 2012292288 A1 20121122; US 9362154 B2 20160607; WO 2011095189 A1 20110811

DOCDB simple family (application)

**DE 102010007127 A 20100205**; CN 201080063106 A 20101123; EP 10787688 A 20101123; EP 2010007098 W 20101123; JP 2012551501 A 20101123; KR 20127017583 A 20101123; SG 2012054839 A 20101123; TW 100104032 A 20110201; US 201013575316 A 20101123